| ASEDCIATION CONNECTING<br>ELECTRONICS INDUSTRESS<br>international and | <b>mposition De</b><br>05. IPC, Bannockt<br>d Pan-American co                                      | claration<br>ourn, Illinois. A<br>opyright conve | All rights reserved u ntions. | nder both         | This docume<br>level parts, th   | ent is a declaration er | on of the substand<br>acompasses all lo | es within the manu<br>wer level materials | afacturer liste<br>for which the | d item. Note: if<br>e manufacturer | the item is an as has engineering | ssembly with low responsibility. |  |
|---|--|--|-------------------------------|-------------------|--|-------------------------|---|---|----------------------------------|------------------------------------|-----------------------------------|----------------------------------|--|
|   | IPC Web Site for Information on IPC-1752 Standard Form Ty<br>http://www.ipc.org/IPC-175x Distribut |  |                               |                   | <ul> <li>Declaration Class *<br/>Class 6 - RoHS Yes/No, Homogeneous Materia</li> </ul> |                         |   |   | Materials and                    | als and Mfg Information            |                                   |                                  |  |
| upplier Information   |  |  |                               |                   |  |                         |   |   |                                  |                                    |                                   |                                  |  |
| ompany name*  | Company unique ID  |  |                               | l                 | Unique ID Authority  |                         |   |   | Response Date*                   |                                    |                                   |                                  |  |
| nsemi   |  |  |                               |                   |  |                         |   |   | 2024-05-21                       |                                    |                                   |                                  |  |
| Contact Name Ti   |  |  | Title - Contact               |                   |  | Phone - Contact*        |   |   |                                  | Email - Contact*                   |                                   |                                  |  |
| Product-Env-Stewards  | Product Enviro Compliance  |  |                               |                   | NA   |                         |   |   | Product-Env-Stewards@onsemi.com  |                                    |                                   |                                  |  |
| uthorized Representative*   | Title - Representative   |  |                               | 1                 | Phone - Representative*  |                         |   | Emai                                      | Email - Representative*          |                                    |                                   |                                  |  |
| roduct-Env-Stewards   | Product Enviro Compliance  |  |                               |                   | NA   |                         |   | Prod                                      | Product-Env-Stewards@onsemi.com  |                                    |                                   |                                  |  |
| Requester Item Number   | Mfr Item   | Number   | Mfr Item Name                 |                   |  | Effective Date          | Version                                 | Manufacturing S                           | lite                             | Weight*                            | UOM                               | Unit Type                        |  |
|   | FGY75T   | FGY75T120SQDN IGBT                               |                               | GBT 1200V 75A UFS |  | 2024-05-21              |   | CP8                                       |                                  | 5456.925                           | mg                                | Each                             |  |
| Ianufacturing Proccess Infor  | mation   |  |                               |                   |  | •                       | -                                       | -   |                                  |                                    |                                   | ·                                |  |
| Terminal Plating / Grid Arra  | Terminal Plating / Grid Array Material Terminal  |  | e Alloy J-STD-020 MSL         |                   | L Rating   | Peak Proce              | Peak Process Body Temperatu             |   | t Peak Tempe                     | rature Numb                        | er of Reflow Cy                   | cles                             |  |
| Matte Tin (Sn) - annealed   |  | CU Alloy NA                                      |                               | NA                |  | 0 C 3                   |   | 30  | sec                              | onds 3                             |                                   |                                  |  |
| omments   |  |  |                               |                   |  |                         |   |   |                                  |                                    |                                   |                                  |  |
|   |  |  |                               |                   |  |                         |   |   |                                  |                                    |                                   |                                  |  |
| or more information regarding mat                                     | erial composition  | please refer to                                  | page 3                        |                   |  |                         |   |   |                                  |                                    |                                   |                                  |  |

| RoHS Material Composition Declaration  |   |  |   | Declaration Type *  | Detailed  |
|--|---|--|---|---|---|
| Directive 2015/863/EU amending RoHS<br>Directive 2011/65/EU  |   | mium (Cr6+), Polybrominated Biphenyls (Pl  |   | dmium and quantity limit of 0.1% by mass (10<br>minated Diphenyl Ethers (PBDE), and Bis(2-et  |   |
| cadmium, hexavalentchromium, polybromina<br>contains a RoHS restricted substance inexces<br>encompass all such components. Supplier cer<br>as of the date that Supplier completes this for<br>Company acknowledges that Supplier may h<br>independently verified information provided<br>certification in this paragraph. If the Company | ated biphenyls and/or polybrominated dip<br>s of an applicable quantity limit, please in<br>ifies that it gathered the information it pr<br>m.Supplier acknowledges that Company<br>ave relied on informationprovided by oth<br>by others, Supplier agrees that, at a minir<br>and the Supplier enter into a written agr<br>esource of the Supplier's liability and the | henyl ethers (each a "RoHS restricted substa<br>ndicate below which, if any, RoHS exemption<br>ovides in this form using appropriate methoo<br>will rely on this certification in determining<br>ers in completing this form, and that Supplie<br>num, itssuppliers have provided certification<br>eement with respect to the identified part, the<br>Company's remedies for issues that arise reg | nce") in exco<br>n you believe<br>ls to ensure i<br>the compliar<br>r may not ha<br>s regarding t<br>terms and co | e may apply. If the part is an assembly with low<br>s accuracy and that such information is true an<br>ce of its products with European Union member<br>de independently verified such information. Ho<br>neir contributions to the part, and those certifica | ove. If a homogeneous material within the part<br>er level components, the declaration shall<br>d correct to the best of its knowledge and belief,<br>er state laws that implement the RoHS Directive.<br>wever, in situations where Supplier has not<br>ations are at least as comprehensive as the<br>anty rights and/or remedies provided as part of |
| RoHS Declaration * 4 - Item(   | s) does not contain RoHS restricted subst   | ances per the definition above except for sele   | ected exempt  | ions Supplier Acceptance  | * Accepted  |
| Exemption: 7a: Lead in high melting temp   | erature type solders (i.e. lead based sol   | der alloys containing 85% by weight or m   | ore lead).  |   |   |
| Exemption List Version   | EL-2011/534/EU  |  |   |   |   |
| Declaration Signature  |   |  |   |   |   |
| Instructions: Complete all of the required<br>Requester) and click on Submit Form to h   |   |  | e drop-dowi   | a. This will display the signature area. Digita   | lly sign the declaration (if required by the  |
| Supplier Digital Signature   | astislav Drska  | Le   |   |   |   |

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

| Homogeneous Material | Weight | Unit of Measure | Level    | Substance   | CAS              | Exempt | Weight    | Unit of Measure |
|----------------------|--------|-----------------|----------|---|------------------|--------|-----------|-----------------|
| Die                  | 32.0   | mg              | Supplier | Silicon (Si)  | 7440-21-3        |        | 32        | mg              |
| Die Attach Solder    | 35.025 | mg              | Supplier | Silver (Ag)   | 7440-22-4        |        | 0.8756    | mg              |
|                      |        |                 | А        | Lead (Pb)   | 7439-92-1        | 7a     | 32.3981   | mg              |
|                      |        |                 | Supplier | Tin (Sn)  | 7440-31-5        |        | 1.7512    | mg              |
| Lead Frame           | 3612.9 | mg              | Supplier | Zinc (Zn)   | 7440-66-6        |        | 1.75      | mg              |
|                      |        |                 | В        | Nickel (Ni)   | 7440-02-0        |        | 117.9998  | mg              |
|                      |        |                 | Supplier | Iron (Fe)   | 7439-89-6        |        | 2.1       | mg              |
|                      |        |                 | Supplier | Copper (Cu)   | 7440-50-8        |        | 3489.9998 | mg              |
|                      |        |                 | Supplier | Phosphorus (P)  | 7723-14-0        |        | 1.05      | mg              |
| Mold Compound-Black  | 1740.0 | mg              | Supplier | Polymer(phenyl glycidil ether)-co-<br>dicyclopentadiene | 119345-05-0      |        | 87        | mg              |
|                      |        |                 | Supplier | Proprietary   | Proprietary Data |        | 87        | mg              |
|                      |        |                 | Supplier | Carbon Black (C)  | 1333-86-4        |        | 8.7       | mg              |
|                      |        |                 | Supplier | Aluminum Hydroxide (Al(OH)3)                            | 21645-51-2       |        | 78.3      | mg              |
|                      |        |                 | Supplier | Fused Silica (SiO2)                                     | 60676-86-0       |        | 1305      | mg              |
|                      |        |                 | Supplier | Ortho-Cresol Novolac Resin                              | 29690-82-2       |        | 87        | mg              |
|                      |        |                 | Supplier | Phenolic Resin (Novolac)                                | 9003-35-4        |        | 87        | mg              |
| Plating              | 31.0   | mg              | Supplier | Tin (Sn)  | 7440-31-5        |        | 31        | mg              |
| Wire Bond - Al       | 6.0    | mg              | Supplier | Aluminum (Al)   | 7429-90-5        |        | 6         | mg              |